

Please amend the above-captioned application as follows:

**IN THE SPECIFICATION**

Please amend the specification, as follows.

Page 1, line 3, ~~replace~~ the heading "TECHNICAL FIELD" with:

---BACKGROUND OF THE INVENTION

1. Field of the Invention---

Page 1, line 10, ~~replace~~ the heading "BACKGROUND ART" with

--- 2. Description of Background Information ---.

Page 4, line 25, ~~replace~~ the heading "DISCLOSURE OF THE INVENTION" with

--- SUMMARY OF THE INVENTION ---.

Page 11, line 13, ~~replace~~ the heading "BEST MODE FOR CARRYING OUT THE INVENTION" with

--- DETAILED DESCRIPTION OF THE INVENTION ---.

Page 50, line 8, ~~delete~~ the heading "INDUSTRIAL APPLICABILITY."

**IN THE CLAIMS**

Please cancel claim ~~20~~

Please amend claims 1-5, 7, 9-14, 16-19, 21, 23-29, and 31-33, as follows. A marked up copy of the amendment is attached as an appendix hereto.

1. A multilayer printed wiring board comprising conductor circuit layers having

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